

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1.-36. (Cancelled).

37. (Currently Amended) A clad board for forming circuitry, ~~the clad board~~ being manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet, the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and

a resin layer formed smoothly on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one of which surface layers is disposed on each face of the inside ~~layer; and~~ layer;

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers; and

wherein the inside layer and the surface layers are made of materials identical to each other.

38.-39. (Cancelled).

40. (Previously Presented) The clad board of claim 37, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

41.-58. (Cancelled).

59. (Previously Presented) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

60.-75. (Cancelled).

76. (Currently Amended) A core board for a clad board for forming circuitry, ~~the core board comprising:~~

a fiber sheet;

the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material ~~comprising~~ including at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and

a resin layer formed on both the top surface and the bottom surface of the fiber sheet, ~~the resin layer being made of material identical to the resin material;~~

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one which surface layers is disposed on each face of the inside layer; and

first and second layers disposed at respective outermost sides of the fiber sheet;

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers; and

wherein the inside layer and the surface layers are made of materials identical to each other.

77.-83. (Cancelled).

84. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a hole formed therein, said core board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

85. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a density ranging from 700 kg/m³ to 1000 kg/m³.

86. (Previously Presented) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

87. (Previously Presented) The core board of claim 76, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

88.-95. (Cancelled).

96. (Previously Presented) The clad board of claim 37, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

97. (Previously Presented) The core board of claim 76, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

98. (Previously Presented) The clad board of claim 37, wherein the non-woven fabric is an aramid fiber non-woven fabric.

99. (Previously Presented) The clad board of claim 98, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m³.

100. (Previously Presented) The clad board of claim 37, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m³.

101. (Previously Presented) The core board of claim 76, wherein the non-woven fabric is an aramid fiber non-woven fabric.

102. (Previously Presented) The core board of claim 101, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m³.

103. (Previously Presented) The core board of claim 76, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m³ and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m³.

104. (Previously Presented) The clad board according to claim 37, wherein the inside layer and the two surface layers include a common resin material and a common non-woven fabric.

105. (Previously Presented) The clad board according to claim 37, wherein the fiber sheet includes a further inside layer, identical in material to the two surface layers, positioned between the inside layer and one of the two surface layers, and having a density lower than a density of either of the two surface layers.